

SOT1149-1

plastic ball grid array package; 708 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA708
Package type industry code	BGA708
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	MS-034D Compliant
JEDEC package outline code	MS-034D Compliant
JEITA package outline code	MS-034D Compliant
Mounting method type	S (surface mount)
Issue date	19-10-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	30.8	-	31	31.2	mm
E	package width	30.8	-	31	31.2	mm
A	seated height	2.22	-	2.37	2.52	mm
A ₂	package height	1.82	-	1.87	1.92	mm
e	nominal pitch	-	-	1	-	mm
n ₂	actual quantity of termination	-	-	708	-	



2. Package outline

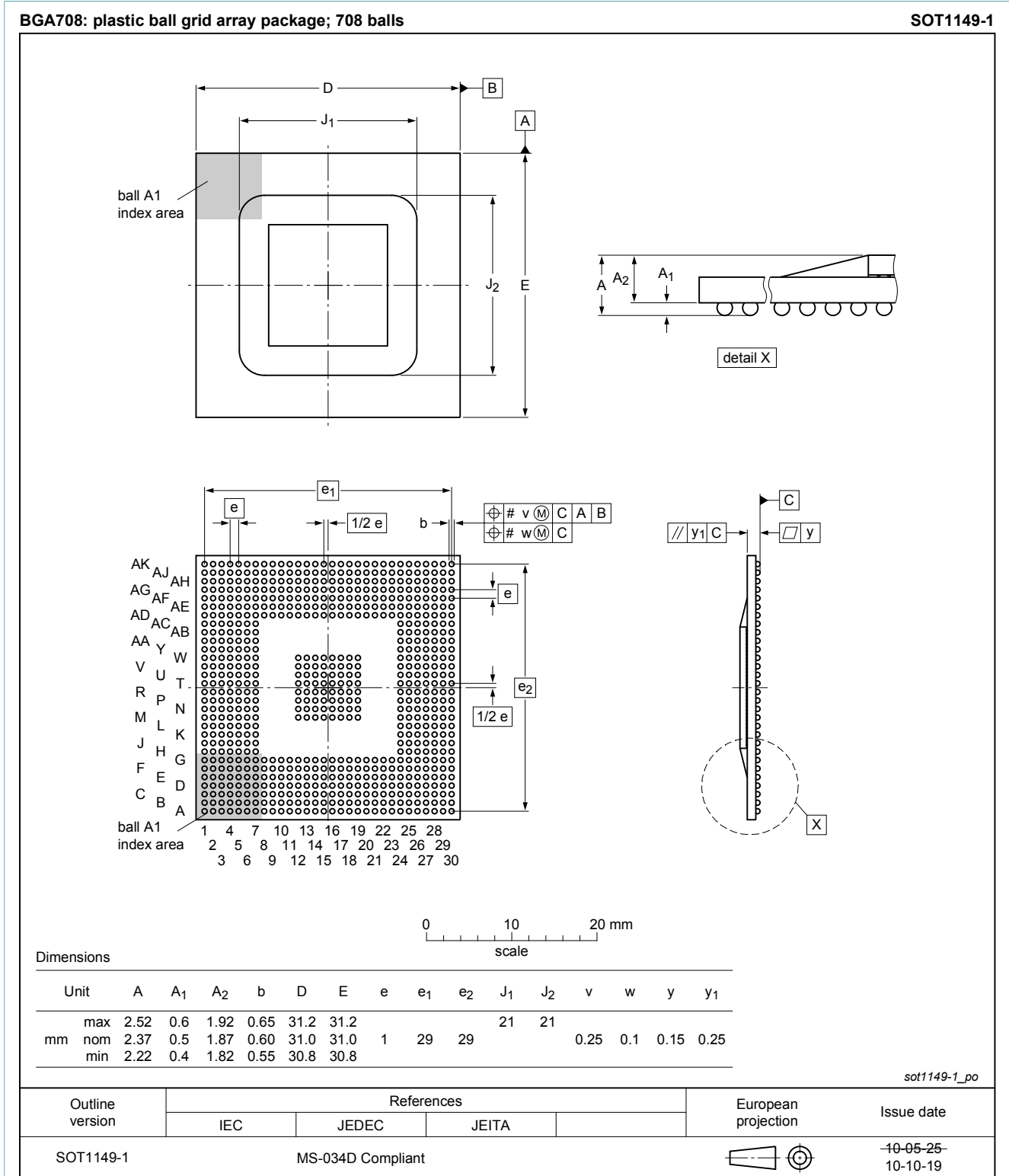


Fig. 1. Package outline BGA708 (SOT1149-1)

3. Legal information

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